Title (en)

MOUNTING STRUCTURE AND MOUNTING PROCESS FROM SEMICONDUCTOR DEVICES

Title (de)

MONTAGE-STRUKTUR UND MONTAGE-VERFAHREN FÜR HALBLEITERANORDNUNG

Title (fr)

STRUCTURE DE MONTAGE ET PROCEDE DE MONTAGE POUR DISPOSITIFS SEMI-CONDUCTEURS

Publication

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Application

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Abstract (en)

[origin: WO9832159A2] The present invention provides a mounting structure for semiconductor devices which enables a semiconductor device, such as CSP/BGA, to be securely fixed to a circuit board by short-time heat curing, which exhibits good productivity, and excellent heat shock properties (or thermal cycle properties), and which permits the semiconductor device to be easily removed from the circuit board in the event of failure. This invention also provides a mounting process for semiconductor devices.

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